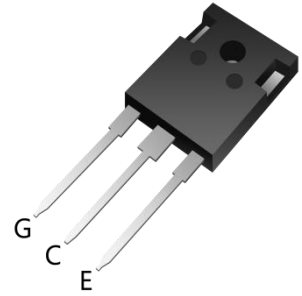
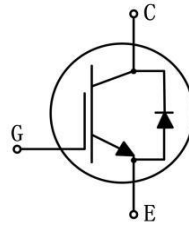


Trench Field-stop IGBT Discrete

Parameter	Value	Unit
V_{CE}	1200	V
I_C	75	A
$V_{CE(sat)}$	1.75	V



TO-247-3L

Features

- Maximum Junction Temperature 175°C
- Low EMI
- Advanced Field Stop Technology
- Pb-free Lead Plating;RoHS Compliant

Applications

- Energy storage
- photovoltaic string inverter
- solar string inverter
- uninterruptible power supply

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CES}	1200	V
Gate-emitter voltage	V_{GES}	±20	V
Continuous collector current($T_C=25^\circ\text{C}$)	I_C	150	A
Continuous collector current($T_C=100^\circ\text{C}$)		75	A
Pulsed Collector Current(Note 1)	I_{CM}	300	A
Diode continuous forward current($T_C=25^\circ\text{C}$)	I_F	150	A
Diode continuous forward current($T_C=100^\circ\text{C}$)		75	A
Maximum Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	750	W
Short circuit withstand time	t_{sc}	10	us
Operating junction temperature range	T_J	-40 to+175	°C
Storage temperature range	T_{STG}	-55 to+150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance,junction to case for IGBT	$R_{\theta JC}$	0.2	°C/W
Thermal resistance,junction to ambient	$R_{\theta JA}$	25	°C/W

Electrical Characteristics of IGBT ($T_{vj}=25^{\circ}\text{C}$ unless otherwise specified)
Static characteristics

Parameter	Symbol	Test condition	Value			Unit
			Min.	Typ.	Max.	
Collector-emitter breakdown voltage	$B_{V_{CES}}$	$V_{GE}=0V, I_C=500\mu A$	1200	-	-	V
Collector-emitter leakage current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$	-	-	200	μA
Gate leakage current, forward	I_{GES}	$V_{GE}=20V, V_{CE}=0V$	-	-	200	nA
Gate Leakage Current, reverse		$V_{GE}=-20V, V_{CE}=0V$	-	-	200	nA
Gate threshold voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=2.4mA$	5	5.8	6.6	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=75A (T_J=25^{\circ}\text{C})$	-	1.75	2.2	V
Total gate charge	Q_G	$V_{CC}=600V, V_{GE}=15V, I_C=75A$	-	540	-	nC
Input Capacitance	C_{ies}	$V_{CE}=25V$	-	5748	-	pF
Output Capacitance	C_{oes}	$V_{GE}=0V$	-	334	-	pF
Reverse Transfer Capacitance	C_{res}	$f=1MHz$	-	185	-	pF

IGBT Switching Characteristics

Parameter	Symbol	Test condition	Value			Unit
			Min.	Typ.	Max.	
Turn-on delay time	$t_{d(on)}$	$V_{CC}=600V$ $V_{GE}=\pm 15V$ $I_C=75A$ $R_G=10\Omega$ Inductive load $T_C=25^{\circ}\text{C}$	-	75	-	ns
Turn-on Rise time	t_r		-	245	-	ns
Turn-off delay time	$t_{d(off)}$		-	172	-	ns
Turn-off Fall time	t_f		-	215	-	ns
Turn-on Switching Loss	E_{on}		-	10.8	-	mJ
Turn-off Switching Loss	E_{off}		-	6.7	-	mJ
Total switching Loss	E_{ts}		-	17.5	-	mJ

Diode Characteristics

Parameter	Symbol	Test condition	Value			Unit
			Min.	Typ.	Max.	
Diode forward voltage	V_F	$I_F=75A, T_{vj}=25^{\circ}\text{C}$	-	1.8	2.5	V
Diode reverse recovery time	t_{rr}	$V_R=600V$	-	60	-	ns
Diode peak reverse recovery current	I_{rr}	$I_F=75A$ $diF/dt=200A/\mu s$	-	50	-	A
Diode reverse recovery charge	Q_{rr}	$T_C=25^{\circ}\text{C}$	-	1200	-	nC

Typical Characteristics

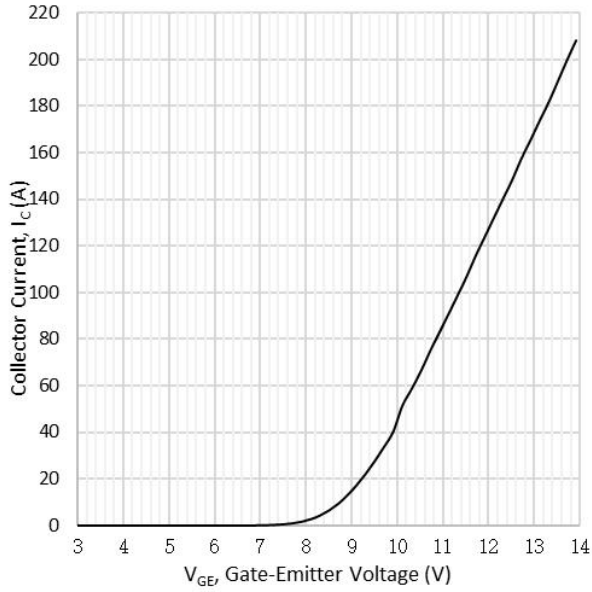


Fig 1. Typical transfer characteristics ($V_{CE}=20V$)

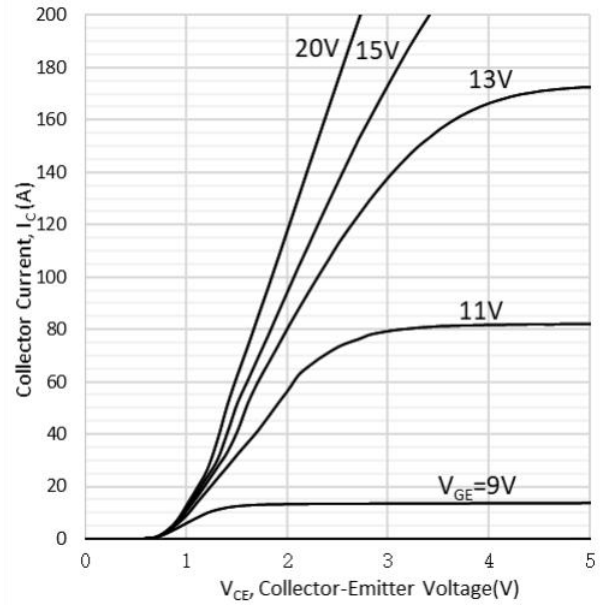


Fig 2. Typical output characteristic ($T_{vj}=25^{\circ}C$)

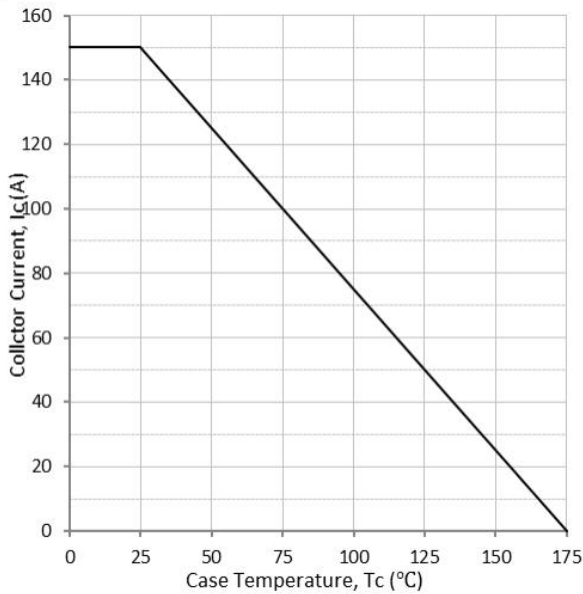


Fig 3. Collector current as a function of case temperature ($V_{GE} \geq 15V, T_{vj} \leq 175^{\circ}C$)

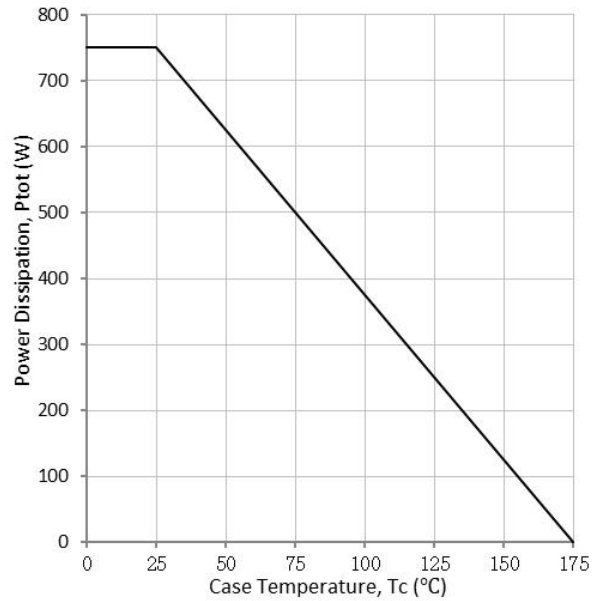


Fig 4. Power dissipation as a function of case temperature ($T_{vj} \leq 175^{\circ}C$)

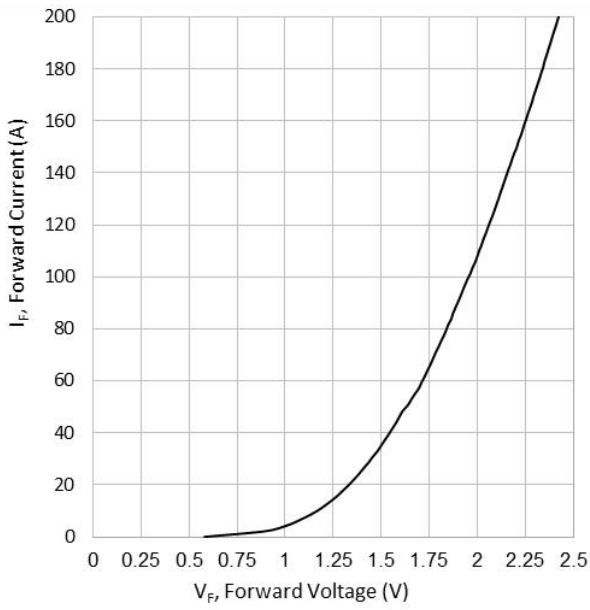


Fig 5. Typical diode forward current vs. forward voltage

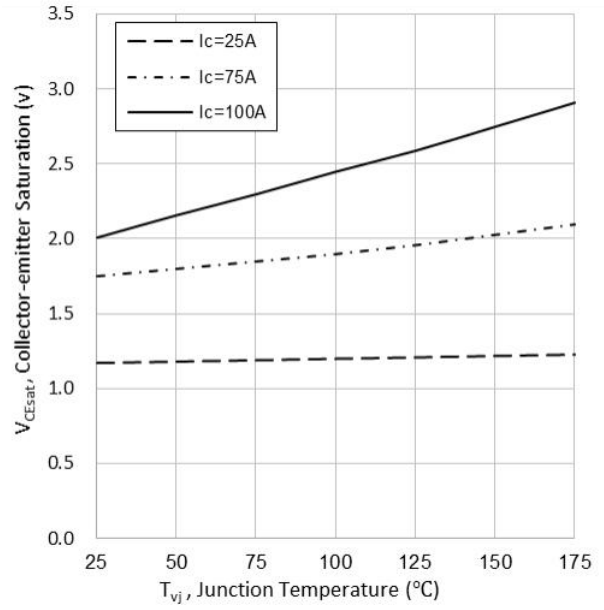


Fig. 6 Typical collector-emitter saturation voltage as a function of junction temperature ($V_{GE}=15V$)

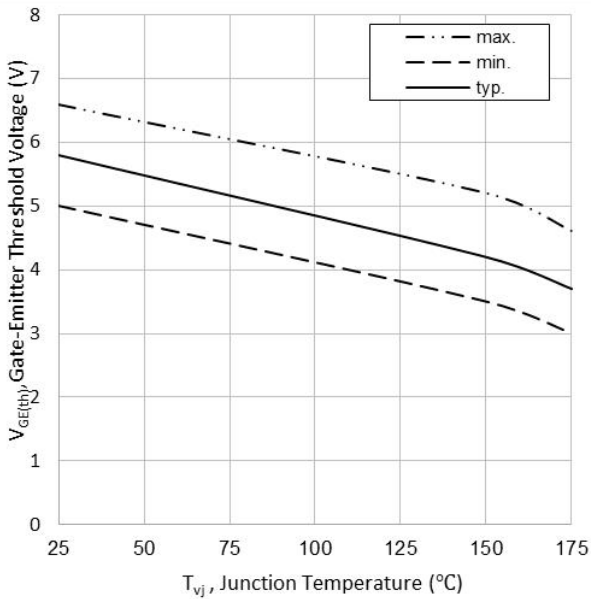


Fig 7. Gate-emitter threshold voltage as a function of junction temperature ($I_C=2.4mA$)

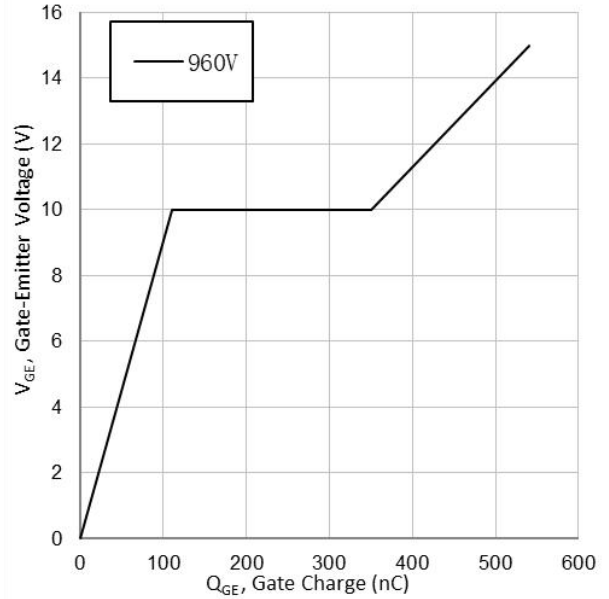


Fig 8. Typical gate charge

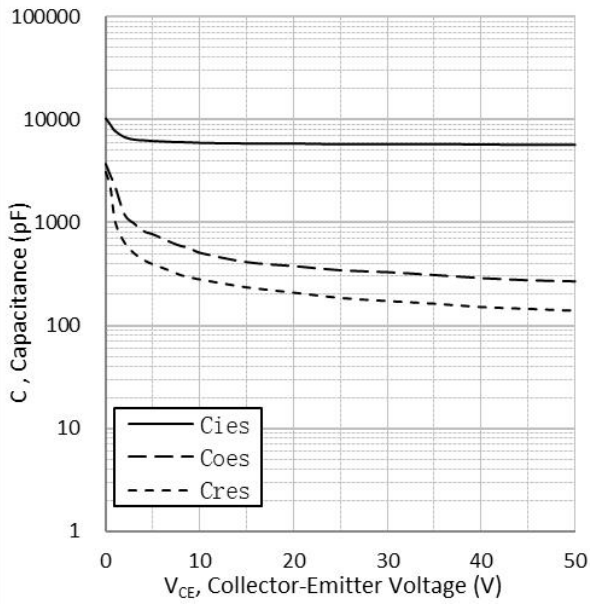
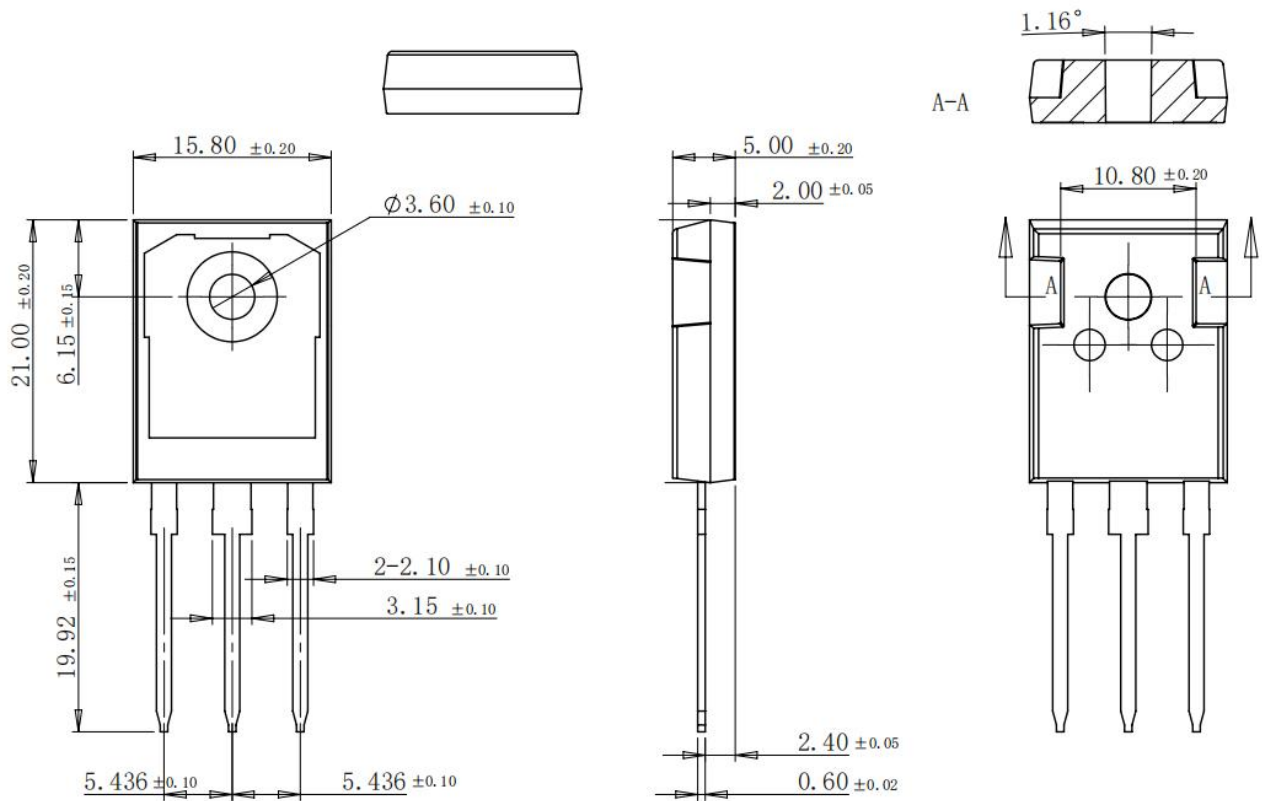


Fig 9. Typical capacitance as a function of collector-emitter voltage ($V_{GE}=0V, f=1MHz$)

Package Outlines (Unit: mm)

TO-247-3L



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